

## HIGH SPEED 2K x 8 CMOS PROM/RPROM

### KEY FEATURES

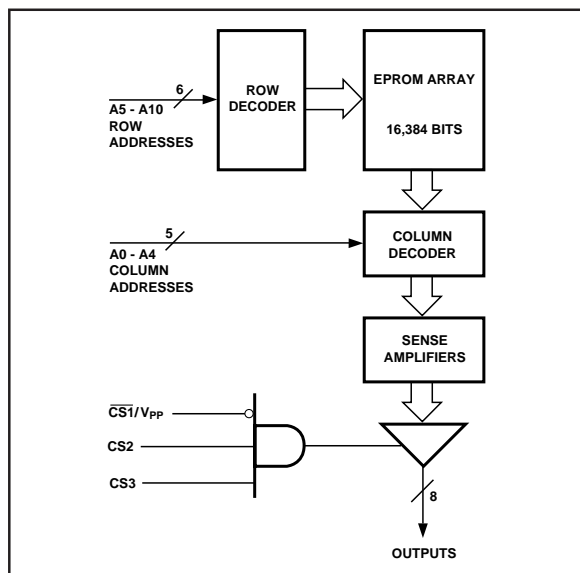
- **Ultra-Fast Access Time**
  - $t_{ACC} = 25 \text{ ns}$
  - $t_{CS} = 12 \text{ ns}$
- **Low Power Consumption**
- **Fast Programming**
- **Available in 300 Mil DIP and PLDCC**
- **Pin Compatible with Am27S191/291 and N82S191 Bipolar PROMs**
- **Immune to Latch-UP**
  - Up to 200 mA
- **ESD Protection Exceeds 2000V**

### GENERAL DESCRIPTION

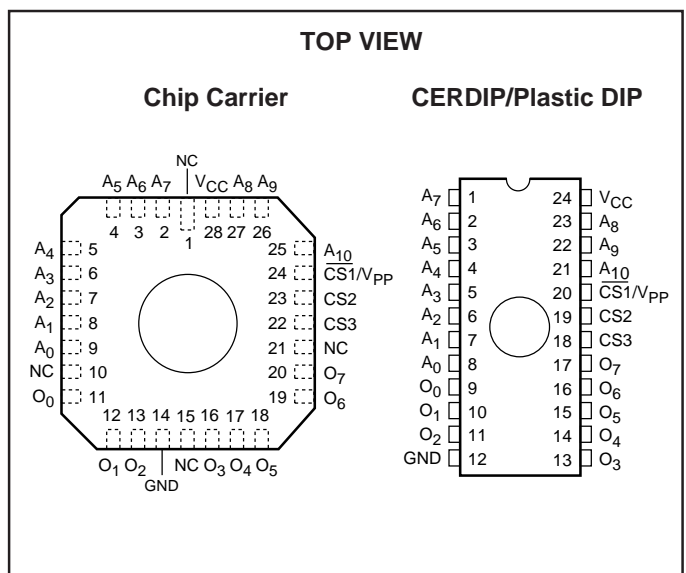
The WS57C191C/291C is an extremely High Performance 16K UV Erasable Electrically Re-Programmable Read Only Memory (RPROM). It is manufactured in an advanced CMOS technology which enables it to operate at Bipolar PROM speeds while consuming only 25% of the power required by its Bipolar counterparts. The WS57C191C/291C is also configured in the standard Bipolar PROM pinout which provides an easy upgrade path for systems which are currently using Bipolar PROMs.

The WS57C191C is packaged in a conventional 600 mil DIP package as well as a Plastic Leaded Chip Carrier (PLDCC) and a Ceramic Leadless Chip Carrier (CLLCC). The WS57C291C is packaged in a space saving 300 mil DIP package configuration. Both are available in commercial, industrial, and military operating temperature ranges.

### BLOCK DIAGRAM



### PIN CONFIGURATION



### PRODUCT SELECTION GUIDE

PARAMETER	191C/291C-25	191C/291C-35	191C/291C-45	191C/291C-55
Address Access Time (Max)	25 ns	35 ns	45 ns	55 ns
CS to Output Valid Time (Max)	12 ns	20 ns	20 ns	20 ns

**ABSOLUTE MAXIMUM RATINGS\***

Storage Temperature.....-65° to + 150°C  
 Voltage on any Pin with Respect to Ground .....-0.6V to +7V  
 $V_{PP}$  with Respect to Ground.....-0.6V to + 14V  
 ESD Protection.....>2000V

**\*NOTICE:**

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect device reliability.

**MODE SELECTION**

<b>PINS</b> <b>MODE</b>	<b>CS1/ <math>\overline{V_{PP}}</math></b>	<b>CS2</b>	<b>CS3</b>	<b>V<sub>CC</sub></b>	<b>OUTPUTS</b>
Read	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IH</sub>	V <sub>CC</sub>	D <sub>OUT</sub>
Output Disable	V <sub>IH</sub>	X	X	V <sub>CC</sub>	High Z
Output Disable	X	V <sub>IL</sub>	X	V <sub>CC</sub>	High Z
Program	V <sub>PP</sub>	X	X	V <sub>CC</sub>	D <sub>IN</sub>
Program Verify	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IH</sub>	V <sub>CC</sub>	D <sub>OUT</sub>
Output Disable	X	X	V <sub>IL</sub>	V <sub>CC</sub>	High Z

**OPERATING RANGE**

<b>RANGE</b>	<b>TEMPERATURE</b>	<b>V<sub>CC</sub></b>
Commercial	0°C to +70°C	+5V ± 10%
Industrial	-40°C to +85°C	+5V ± 10%
Military	-55°C to +125°C	+5V ± 10%

**DC READ CHARACTERISTICS** Over Operating Range. (See Above)

<b>SYMBOL</b>	<b>PARAMETER</b>	<b>TEST CONDITIONS</b>	<b>MIN</b>	<b>MAX</b>	<b>UNITS</b>
V <sub>IL</sub>	Input Low Voltage	(Note 3)	-0.1	0.8	V
V <sub>IH</sub>	Input High Voltage	(Note 3)	2.0	V <sub>CC</sub> + 0.3	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 16 mA		0.4	V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -4 mA	2.4		V
I <sub>CC1</sub>	V <sub>CC</sub> Active Current (CMOS)	V <sub>CC</sub> = 5.5V, f = 0 MHz (Note 1), Output Not Loaded Add 2mA/MHz for AC Operation	Comm'l	30	mA
			Industrial	35	mA
			Military	35	mA
I <sub>CC2</sub>	V <sub>CC</sub> Active Current (TTL)	V <sub>CC</sub> = 5.5V, f = 0 MHz (Note 2), Output Not Loaded Add 2mA/MHz for AC Operation	Comm'l	40	mA
			Industrial	50	mA
			Military	50	mA
I <sub>LI</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5V or Gnd	-10	10	µA
I <sub>LO</sub>	Output Leakage Current	V <sub>OUT</sub> = 5.5 V or Gnd	-10	10	µA

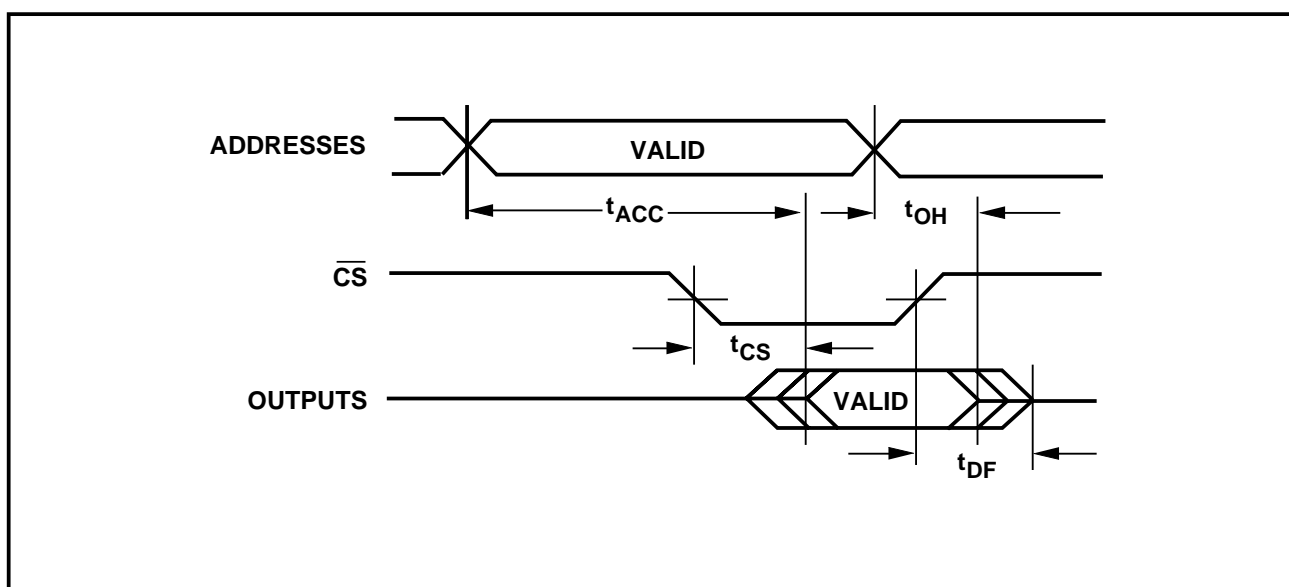
- NOTES:**
1. CMOS inputs: GND ± 0.3V or V<sub>CC</sub> ± 0.3V.
  2. TTL inputs: V<sub>IL</sub> ≤ 0.8V, V<sub>IH</sub> ≥ 2.0V.
  3. These are absolute voltages with respect to device ground pin and include all overshoots due to system and/or tester noise. Do not attempt to test these values without suitable equipment.



**AC READ CHARACTERISTICS** Over Operating Range. (See Above)

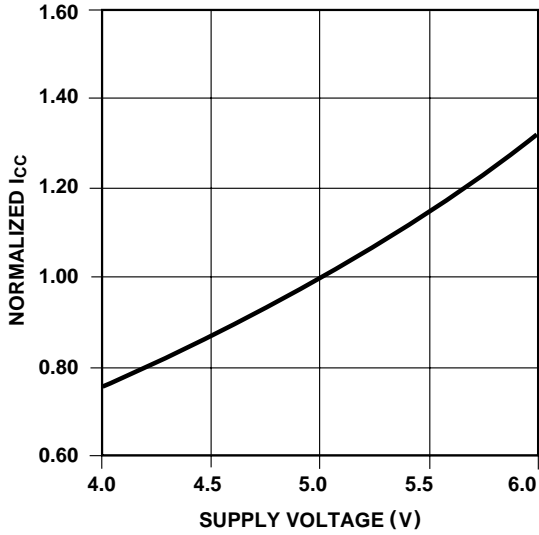
PARAMETER	SYMBOL	191C/291C-25		191C/291C-35		191C/291C-45		191C/291C-55		UNITS
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
Address to Output Delay	$t_{ACC}$		25		35		45		55	ns
$\overline{CS}$ to Output Delay	$t_{CS}$		12		20		20		20	
Output Disable to Output Float*	$t_{DF}$		12		20		20		20	
Address to Output Hold	$t_{OH}$	0		0		0		0		

\*Sampled, Not 100% Tested

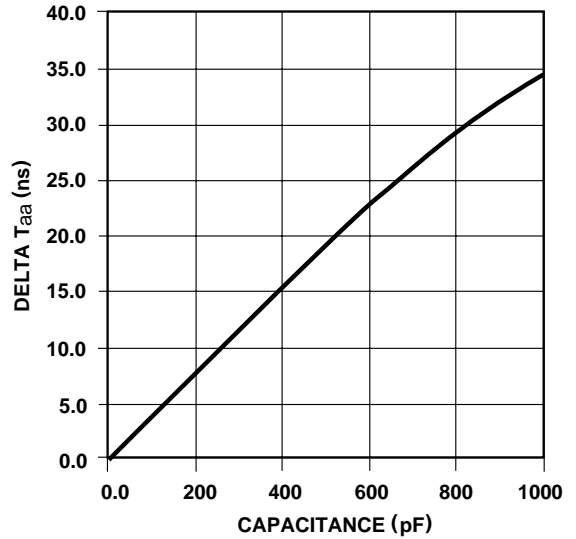
**AC READ TIMING DIAGRAM**



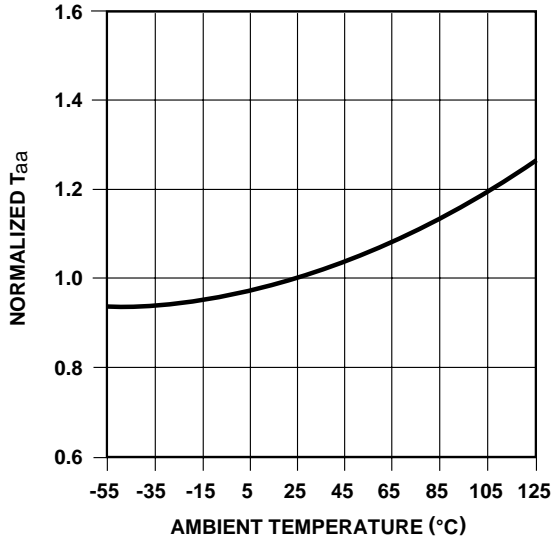
**NORMALIZED SUPPLY CURRENT  
vs.  
SUPPLY VOLTAGE**



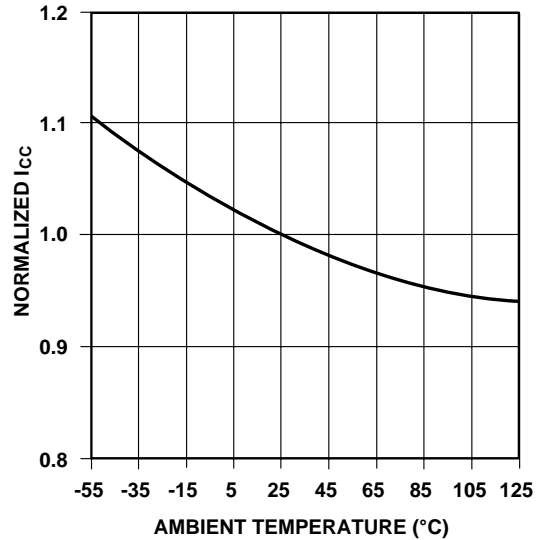
**TYPICAL ACCESS TIME CHANGE  
vs.  
OUTPUT LOADING**



**NORMALIZED T<sub>aa</sub>  
vs.  
AMBIENT TEMPERATURE**



**NORMALIZED SUPPLY CURRENT  
vs.  
AMBIENT TEMPERATURE**



**PROGRAMMING INFORMATION**

**DC CHARACTERISTICS** ( $T_A = 25 \pm 5^\circ\text{C}$ ,  $V_{CC} = 6.25 \text{ V} \pm 0.25 \text{ V}$ ,  $V_{PP} = 12.75 \pm 0.25 \text{ V}$ )

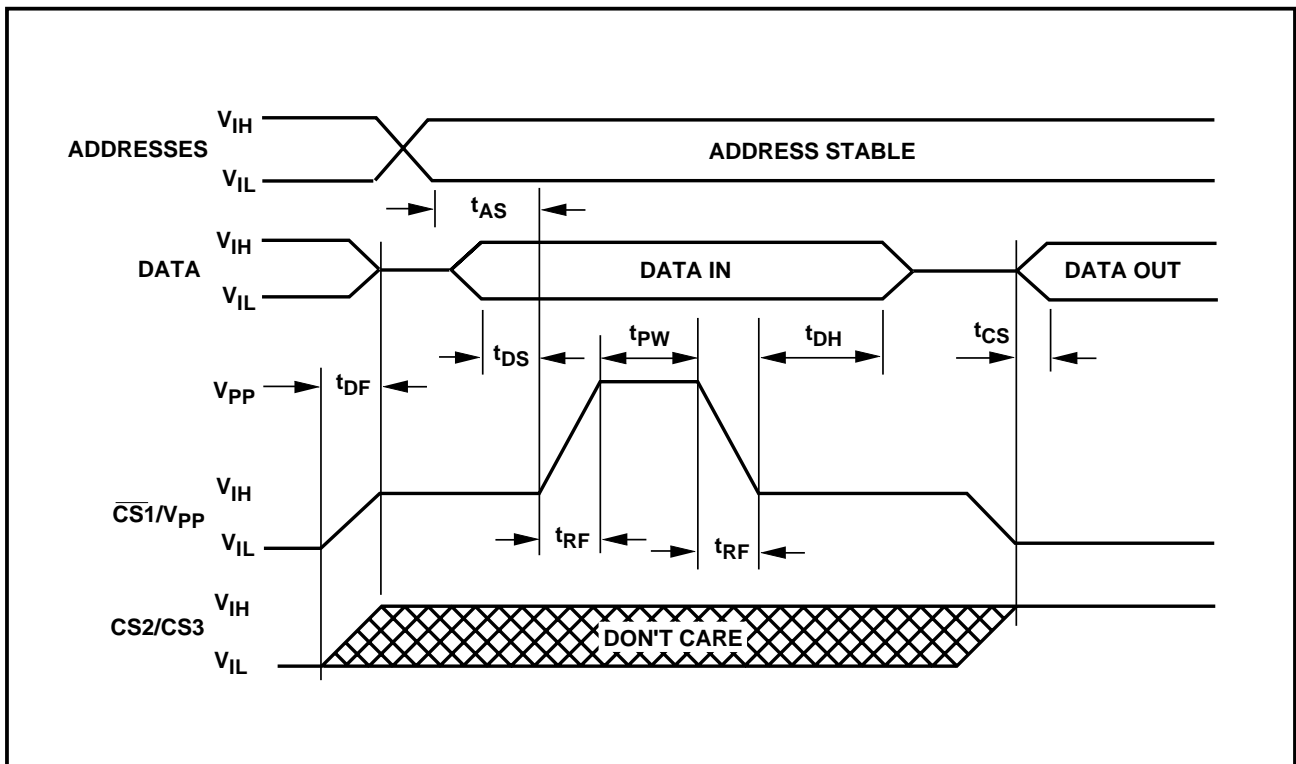
SYMBOLS	PARAMETER	MIN	MAX	UNITS
$I_{LI}$	Input Leakage Current ( $V_{IN} = V_{CC}$ or Gnd)	-10	10	$\mu\text{A}$
$I_{PP}$	$V_{PP}$ Supply Current During Programming Pulse		60	mA
$I_{CC}$	$V_{CC}$ Supply Current		25	mA
$V_{OL}$	Output Low Voltage During Verify ( $I_{OL} = 16 \text{ mA}$ )		0.45	V
$V_{OH}$	Output High Voltage During Verify ( $I_{OH} = -4 \text{ mA}$ )	2.4		V

NOTES: 8.  $V_{PP}$  must not be greater than 13 volts including overshoot.

**AC CHARACTERISTICS** ( $T_A = 25 \pm 5^\circ\text{C}$ ,  $V_{CC} = 6.25 \text{ V} \pm 0.25 \text{ V}$ ,  $V_{PP} = 12.75 \pm 0.25 \text{ V}$ )

SYMBOLS	PARAMETER	MIN	TYP	MAX	UNITS
$t_{AS}$	Address Setup Time	2			$\mu\text{s}$
$t_{DF}$	Chip Disable Setup Time			30	ns
$t_{DS}$	Data Setup Time	2			$\mu\text{s}$
$t_{PW}$	Program Pulse Width	100		200	$\mu\text{s}$
$t_{DH}$	Data Hold Time	2			$\mu\text{s}$
$t_{CS}$	Chip Select Delay			30	ns
$t_{RF}$	$V_{PP}$ Rise and Fall Time	1			$\mu\text{s}$

**PROGRAMMING WAVEFORM**



**ORDERING INFORMATION**

PART NUMBER	SPEED (ns)	PACKAGE TYPE	PACKAGE DRAWING	OPERATING TEMPERATURE RANGE	WSI MANUFACTURING PROCEDURE
<b>WS57C191C</b>					
WS57C191C-25D	25	24 Pin CERDIP, 0.6"	D1	Comm'l	Standard
WS57C191C-25J	25	28 Pin PLDCC	J3	Comm'l	Standard
WS57C191C-25P	25	24 Pin Plastic DIP, 0.6"	P2	Comm'l	Standard
WS57C191C-35D	35	24 Pin CERDIP, 0.6"	D1	Comm'l	Standard
WS57C191C-35J	35	28 Pin PLDCC	J3	Comm'l	Standard
WS57C191C-35P	35	24 Pin Plastic DIP, 0.6"	P2	Comm'l	Standard
WS57C191C-45D	45	24 Pin CERDIP, 0.6"	D1	Comm'l	Standard
WS57C191C-45DI	45	24 Pin CERDIP, 0.6"	D1	Industrial	Standard
WS57C191C-45DMB*	45	24 Pin CERDIP, 0.6"	D1	Military	MIL-STD-883C
WS57C191C-45J	45	28 Pin PLDCC	J3	Comm'l	Standard
WS57C191C-45P	45	24 Pin Plastic DIP, 0.6"	P2	Comm'l	Standard
WS57C191C-55D	55	24 Pin CERDIP, 0.6"	D1	Comm'l	Standard
WS57C191C-55DMB*	55	24 Pin CERDIP, 0.6"	D1	Military	MIL-STD-883C
<b>WS57C291C</b>					
WS57C291C-25S	25	24 Pin Plastic DIP, 0.3"	S1	Comm'l	Standard
WS57C291C-25T	25	24 Pin CERDIP, 0.3"	T1	Comm'l	Standard
WS57C291C-35S	35	24 Pin Plastic DIP, 0.3"	S1	Comm'l	Standard
WS57C291C-35T	35	24 Pin CERDIP, 0.3"	T1	Comm'l	Standard
WS57C291C-35TMB*	35	24 Pin CERDIP, 0.3"	T1	Military	MIL-STD-883C
WS57C291C-45S	45	24 Pin Plastic DIP, 0.3"	S1	Comm'l	Standard
WS57C291C-45T	45	24 Pin CERDIP, 0.3"	T1	Comm'l	Standard
WS57C291C-45TI	45	24 Pin CERDIP, 0.3"	T1	Industrial	Standard
WS57C291C-45TMB*	45	24 Pin CERDIP, 0.3"	T1	Military	MIL-STD-883C
WS57C291C-55T	55	24 Pin CERDIP, 0.3"	T1	Comm'l	Standard
WS57C291C-55TMB*	55	24 Pin CERDIP, 0.3"	T1	Military	MIL-STD-883C

**NOTE:** 9. The actual part marking will not include the initials "WS."

\*SMD product. See section 4 for DESC SMD number.

**PROGRAMMING/ALGORITHMS/ERASURE/PROGRAMMERS**

**REFER TO  
PAGE 5-1**

The WS57C191C and WS57C291C are programmed using Algorithm D shown on page 5-9.